PCN Number:		20160217000			PCN Date:		03/07/2016	
Title	: Datasheet for	TPS92661-Q1						
Customer Contact: PCN Man		PCN Manager	<u>er</u>		ept: Qua		ity Services	
	nge Туре:							
	Assembly Site		Design			Wafer Bump Site		
	Assembly Process			<u>Ц</u>		fer Bump Material		
	Assembly Material		Part number change	<u> </u>		Vafer Bump Process		
	Mechanical Specifi		Test Site	<u> </u>		Wafer Fab Site		
	Packing/Shipping/	Labeling	Test Process	+	Wafer Fab Materials			
							rocess	
Notification Details  Description of Change:								
Texas Instruments Incorporated is announcing an information only notification.  The product datasheet(s) is updated as seen in the change revision history below:								
TEXAS INSTRUMENTS  TPS92661-Q1  SLUSBU2A-SEPTEMBER 2014-REVISED FEBRUARY 2016  www.ti.com								
Changes from Original (September 2014) to Revision A Page						Page		
Added output current range specifications in Recommended Operating Conditions table								
Dev	vice Family Cha		Change From:	rom:			Change To:	
	TPS92661-Q1		SLUSBU2		SLUSBU2A			
These changes may be reviewed at the datasheet links provided. <a href="http://www.ti.com/product/tps92661-q1">http://www.ti.com/product/tps92661-q1</a> Reason for Change:								
To more accurately reflect device characteristics.								
Anti	cipated impact o	n Fit, Form, Fu	unction, Quality or Reliab	ility	/ (posit	ive /	negative):	
No a			cation change announceme					
Changes to product identification resulting from this PCN:								
None.								
Product Affected:								
TPS9	2661QPHPRQ1							

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com